



## Advance Product Change Notification

201507030A

**Issue Date:** 16-Aug-2015

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For detailed information we invite you to view this notification online



# QUALITY

### Management Summary

Change of bond wire material from Au to Cu, release of 2nd source mold compound, and 2nd source assembly and final test location for dedicated product types in SOT363 package

#### Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input checked="" type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

**Change of bond wire from Au to Cu and release of 2nd source assembly location SOT363**

### Details of this Planned Change

Scheduled changes affect product types in SOT363 (SC-88) package only.

- (1) The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons only.
- (2) A second source mold compound supplier will be introduced for copper wire products.
- (3) Release of NXP Assembly Plant Guangdong (APG), China, as second source of assembly and final test in addition to current location NXP Assembly Plant Seremban (APM), Malaysia.

Old product: wire material is Au (with currently used mold compound suppliers); assembly in APM

Changed product: wire material is Cu (with currently used first and new second source mold compound supplier) or Au (with currently used mold compound suppliers); assembly in APM or APG

The existing processes from APM are copied exactly at APG. Both locations will operate under the same conditions, with same equipment and processes, at equal performance and with comparable systems.

The design and materials of all other components will remain unchanged, i.e. no change of die, die attach, and lead frame. Reliability qualification and full electrical characterization over temperature are performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

#### Why do we Plan this Change

- (1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
- (2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM. The second source is already a well-established mold compound supplier for NXP GA discrete semiconductor products.
- (3) The implementation of the second source assembly center will increase production capacity and flexibility to ensure fulfillment of customer demands.

#### Identification of Affected Products

Changed products can be identified by date code after implementation.  
Assembly location can be tracked by vendor code on package surface and is also stated on packing labels.

## Product Availability

### Sample Information

Samples are available upon request  
Samples can be ordered now and will be shipped after FPCN issue date.

### Production

Planned first shipment 01-Feb-2016

## Impact

No impact to the products' functionality anticipated.

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Related Notifications

### Notification Issue Date Effective Date Title

201410006F0129	Nov-2014	10-Mar-2015	Change of bond wire to copper and release of 2nd mold compound in SOT323 and SOT363
201411005F0126	Jan-2015	10-May-2015	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT363

## Timing and Logistics

The Self Qualification Report will be ready on 12-Oct-2015.  
The Final PCN is planned to be issued on: 12-Oct-2015.  
Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 15-Sep-2015.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support  
**e-mail address** DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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NXP Semiconductors  
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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